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## APPLICANTS

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*YES 6/13/2006*

## \*\* CONTINUING DATA \*\*\*\*\*

This application is a DIV of 10/187,269 07/02/2002 PAT 6,734,549

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

JAPAN 2001-201950 07/03/2001

*YES 6/13/2006*

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 06/28/2004

Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	6/13/06	STATE OR COUNTRY	SHEETS DRAWING	TOTAL CLAIMS	INDEPENDENT CLAIMS
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance		JAPAN	25	12	5
Verified and Acknowledged	<i>[Signature]</i>	<i>[Initials]</i>				

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## TITLE

Semiconductor wiring substrate, semiconductor device, method for testing semiconductor device, and method for mounting semiconductor device

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